APPLICA	BLE STAN	IDARD									
OPERATING TEMPERATUR		RE RANGE	-30°C TO + 85°C (NOTE 1)		STORAGE TEMPERAT	URE RANG	E -1	-10°C TO + 60°C (NOTE			
	OPERATING HUMIDITY RANGE		40% TO 80% (NO	TE 2)	STORAGE HUMIDITY F			40% TO 70% (NOTE 3)			
RATING	VOLTAGE		250V AC		APPLICABL CONNECTO			DF3-*S-2C			
	CURRENT		3 A								
			SPEC	IFICAT	IONS		·				
	EM		TEST METHOD			REQUIREMENTS				АТ	
	RUCTION	Luguarta	AND BY MEA GUDING INGTOLI		1,000	DDING T		1110	Тх	T	
GENERAL EXAMINATION MARKING			VISUALLY AND BY MEASURING INSTRUMENT. CONFIRMED VISUALLY.			ACCORDING TO DRAWING.				X	
ELECTRIC CHARA									X		
		100mA (DC OR 1000 Hz). 30mΩ MAX.							X	l _	
INSULATIO		500V DC.			1000	1000MΩ MIN.				<u> </u>	
RESISTANCE VOLTAGE PROOF		650V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.				<u> </u>	
MECHAN	IICAL CH	ARACT	RACTERISTICS								
MECHANIC.		30 TIMES INSERTIONS AND EXTRACTIONS.				① CONTACT RESISTANCE: 30mΩ MAX.					
OPERATION					② NO OF	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				_	
VIBRATION			FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS 				_	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				OF PARTS.				_	
ENVIRO	NMENTA		ACTERISTICS						X		
RAPID CHANGE OF		TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35 °C			I .	NTACT RE			X		
TEMPERATURE			TIME $30 \rightarrow 5 \text{ MAX} \rightarrow 30 \rightarrow 5 \text{ MAX min}$ UNDER 5 CYCLES.			 ☑ INSULATION RESISTANCE: 1000MΩ MIN. ⑤ NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			② IN: ③ NO OF	 CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 500MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_	
RESISTANCE TO SOLDERING HEAT		1) AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE, 260 °C FOR IMMERSION, DURATION, 5 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :300 °C, SOLDERING TIME :2sec. NO STRENGTH ON CONTACT.			EXCE	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				_	
SOLDERABILITY			OLDERED AT SOLDER TEMPERATURE, 230°C FOR INSERTION DURATION, 3sec.			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				-	
NOTE2:NO NOTE3:APF BEF	CONDENSIN LY TO THE (ORE PCB O	G. CONDITION N BOARD A	ATURE RISE BY CURRENT NOF LONG TERM STORAG FTER PCBBOARD, OPER IED FOR INTERM STORAG	SE FOR UI	NUSED PRO	DDUCTS E AND			1	1	
COUN	Т	ESCRIPTI	ON OF REVISIONS		ESIGNED			CHECKED	DA	DATE	
I Inless oth	nwise ses		6-H-000745			APPROVES.		TV 000	06.08.31		
oniess oth	erwise spec	ыни , reter	to JIS C 5402.			APPRON CHECK DESIGN DRAW	ED IED	TY.OMA HK.UMEHARA TS.KUMAZAWA AK.MIURA	06.0	08.31 08.31 08.29 08.29	
Note QT:Q	ualification Te	cation Test AT:Assurance Test X:Applicable Test				RAWING NO. ELC4-162					
3 L 🔾		PECIFI	PECIFICATION SHEET				DF3A-*P-2DSA				
			LECTRIC CO., LTD.		ODE NO.	CL543		◬	1/1		
ENDM HDDO11.	^ 1				_	_	_				